EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1817	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:15
L2	1611	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and (drie\$1 dry\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 06:53
L3	20	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and (drie\$1 dry\$3) and "34"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 07:03
L4	277	komatsu.as. and (mikio.in. akihiro.in.)	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 07:04
L5	0	komatsu.as. and (mikio.in. akihiro.in.) and 1	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:03
L6	0	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and 4	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 07:04
L7	0	(substrate wafer semiconductor) and vapor and inert and (gas nirtrogen helium argon) and nozzle and 4	US-PGPUB; USPAT; FPRS; EPO; JPO	OR ,	OFF	2007/06/06 07:05
L8	0	(substrate wafer semiconductor) and vapor and inert and nozzle and 4	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 07:05
L9	71	(substrate wafer semiconductor) and 4	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 07:05
L10	17	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and (komatsu.as. (mikio.in. akihiro.in.))	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 08:38

SMA

EAST Search History

L11	1759	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and heat\$3	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 08:48
L12	106	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and heat\$3 and "134"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 08:49
L13	16	(substrate wafer semiconductor) and vapor and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3 and heat\$3 and "34"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 08:49
L14	17	("5884640").URPN.	USPAT	OR	OFF	2007/06/06 08:53
L15	10	("4643774" "4714086" "4984597" "5520744" "5569330" "5575079" "5660642" "5714203" "5752532" "5807439").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/06/06 08:54
L16	5	("4876801" "5268036" "5884640" "5950328" "6494220").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/06/06 08:57
L17	17	(komatsu.as. (mikio.in. akihiro.in.)) and 1	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:04
L18	9	("6412501").URPN.	USPAT	OR	OFF	2007/06/06 09:04
L19	17	("3923541" "5884640" "5934299" "5938857" "5940985" "5950646" "5951779" "6001191" "6045621" "6045624" "6050275" "6082381" "6108928" "6143087" "6145519" "6152153" "6216364").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/06/06 09:04
L20	94	(substrate wafer semiconductor) and vapor with (gas inert) with mixture and (solvent ipa cipa isopropyl alcohol) and inert and (gas nirtrogen helium argon) and nozzle and bubbl\$3	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:33
L21	19	("4791273" "4993361" "5224202" "5277938" "5356673" "5361800" "5362328" "5372754" "5383970" "5405659" "5419924" "5421895" "5447569" "5451258" "5451260" "5476547" "5529634" "5835677" "5882416").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/06/06 09:28

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L22	0	(substrate wafer semiconductor) and vapor with (gas inert) with mixture and (solvent ipa cipa isopropyl alcohol) and "344"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:34
L23	47	(substrate wafer semiconductor) and vapor with (gas inert) with mixture and (solvent ipa cipa isopropyl alcohol) and "34"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:36
L24	143	(substrate wafer semiconductor) and vapor with (gas inert) with mixture and (solvent ipa cipa isopropyl alcohol) and "134"/\$.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO	OR	OFF	2007/06/06 09:34
L25	4	(("5884640") or ("5950328") or ("6412501") or ("6050275")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/06/06 09:36